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Find the Asyst Technologies LPT 2200 at our website: **Click HERE**
The Model 9350 Laser Semiconductor Processing System from ESI offers superior results for throughput, yield and uptime performance. The patented application of the 1.3 µm wavelength laser provides critical process window capability for metal memory link materials, allowing higher levels of energy to be used to remove links without damaging the surrounding silicon. The result is cleaner link cuts with higher yields. In addition, the Model 9350 provides high accuracy positioning and continuous wafer processing.

New features of the Model 9350 include a 2.3 µm laser spot for smaller link pitches to accommodate the latest semiconductor device shrinks. A higher rep rate laser and faster embedded controller with new software also provide substantial throughput improvements. The result is a lower cost of ownership combined with the very latest technology for improving the yield on memory devices.
SPECIFICATIONS

**SUMMARY**

**1.3 µm Wavelength**
Patented application of 1.3 µm wavelength laser

**Programmable Spot Size**
Programmable Range: 2.3 µm to 6.0 µm (1/e²)
Programmable Resolution: 0.1 µm

**Laser and Energy Density Control**
Type: Diode-pumped 1.3 µm wavelength laser with acousto-optic Q-switch and an air-cooled power supply
Pump Source Lifetime: Greater than 10,000 hours guaranteed
Energy Control: Continuously variable up to a maximum setting of 6.0 µJ per pulse
Laser Focus: High-speed, high-resolution focusing maintains greater than 95% of the maximum energy density at focus
Laser Pulsewidth Options: 6.5, 9.5, or 15 ns at 6000 Hz

**Application Environment**
Turnkey Software: Includes concurrent setup, runtime, calibration, and diagnostic programs for fast device setup and process optimization
Operator Local Language Support: Japanese, Korean and German
Engineering Tools: ESI’s EasyAlg™ redundancy algorithm development tools eliminates C programming requirements for device setup. ESI’s Variable Multiple Die Alignment optimizes die throughput by minimizing alignment overhead
Automatic Wafer Handling
Continuous wafer processing
Improved thin wafer handling capability
Link Inspection Option: Provides the ability to inspect link blow quality using a color, high resolution (< 0.5 mm), (1000X to 4500X zoom), built-in microscope
Wafer ID Reading and Illumination Option
SEMI character font with checksum and single character error correction routines
ScribeView™ patented programmable OCR illumination subsystem

**System Enclosure – Self Contained Environment**
Standards: CE Mark compliant SEMI S2-93
ESD Tolerance: System certified to withstand up to 8 KV discharge without any effect to production operation
Static Control: Particulate-free ionizer option for removing static charge on incoming wafers
Vibration: Internal air table used for active vibration isolation

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**Laser Beam Positioning**
Type: High-performance brushless DC linear motor with independent X and Y axes, new laser dual path interferometer closed-loop position control
Total Positioning Accuracy: Better than 0.35 µm, mean plus 3 σ, over any 35 mm x 35 mm field, 0.5 µm mean plus 3 σ over 200 mm wafer field
Field of Travel: 204 mm (x) 240 mm (y)

**System Control Computer**
Type: Hewlett Packard VME workstation with color monitor. UNIX operating system
User Interface: OSF/Motif environment
Networking: Ethernet (ThickLAN, ThinLAN, or Twisted-Pair) with FTP and NSF protocols

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